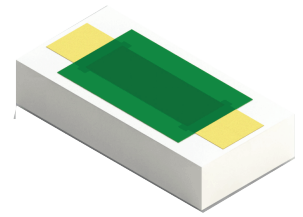


RM2010ZZ-XXXXWN-99-02 Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)



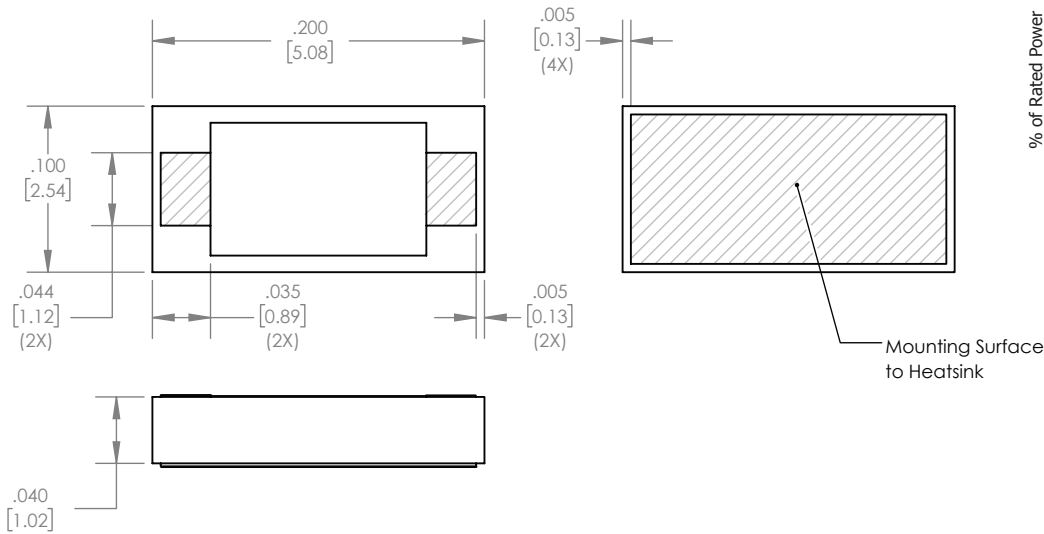
Actual Size

RM2010ZZ-XXXXWN-99-02 Parameters:

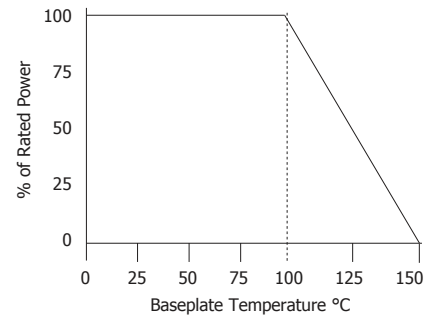
Resistance Range:	0.5Ω - 1MΩ
Rated Power:*	40W
Construction:	Thick Film on 0.040" BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM2010ZZ-XXXXWN-99-02 Dimensions:



RM2010ZZ-XXXXWN-99-02 Power Derating Curve



Dimensions in inches [mm]
Tolerance is ± 0.005 [0.13]
unless otherwise stated

Ordering Information:

Example Part Number: RM2010CT-50R0JN-99-02

RM	2010	ZZ	-	XXXX	W	N	-	99	-02	UU
Prefix for Resistor w/ Single-Sided Terminals and Backplane	Size	Value Code		Tolerance	Normal Inspection	Substrate	Assigned by			Packaging
	2010	50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ 1004 - 1MΩ		F - 1% G - 2% J - 5%	Contact factory for additional options	99 - 0.040" BeO	Factory			Blank - Bulk WP - Waffle Pack TR - Tape & Reel

Terminal Metallization

Terminal	Metallization	RoHS	Magnetic	Solder	Epoxy	Wirebond
AS	Tin Lead over Platinum Palladium Gold	No	No	Yes	No	No
CB	Tin Lead over Nickel over Silver	No	Yes	Yes	No	No
CC	100% Matte Tin over Copper over Silver	Yes	No	Yes	No	No
CT	100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	No
HA	Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane	Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
JA	Gold over Platinum Palladium Gold	Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RM2010ZZ-XXXXWN-99-02 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 Para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202-210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +150 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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